

(0.635 mm) .025"

QTS SERIES

HIGH-SPEED GROUND PLANE HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com/QTS

Insulator Material:
Liquid Crystal Polymer
Contact Material:
Phosphor Bronze

Plating:
Au or Sn over
50 μ " (1.27 μ m) Ni
Current Rating:
Contact:
1.8 A per pin
(2 pins powered)
Ground Plane:
23.1 A per ground plane
(1 ground plane powered)

Operating Temp:
-55 °C to +125 °C
Voltage Rating:
285 VAC

Max Cycles:
100

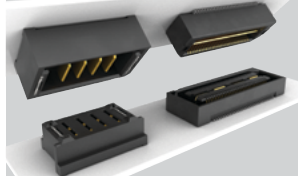
RoHS Compliant:
Yes

Board Mates:
QSS

Cable Mates:
SQCD

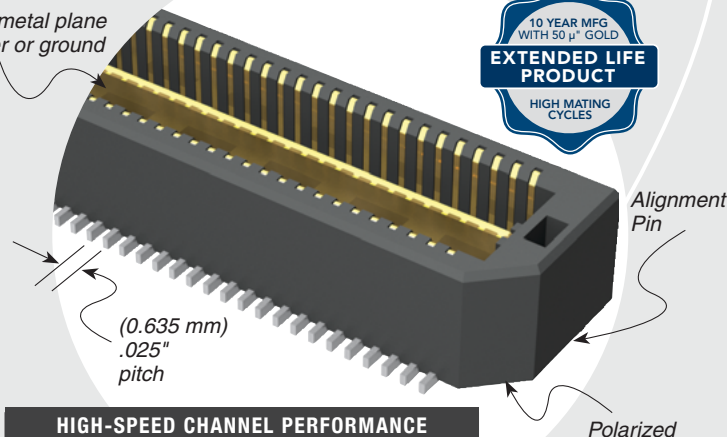
Standoffs:
SO

POWER/SIGNAL APPLICATION



Compatible with
UMPT/UMPS for flexible
two-piece power/signal solutions

Integral metal plane
for power or ground



HIGH-SPEED CHANNEL PERFORMANCE

QTS/QSS @ 5 mm Mated Stack Height
Rating based on Samtec reference channel.
For full SI performance data visit Samtec.com
or contact SIG@samtec.com

25
Gbps

PROCESSING

Lead-Free Solderable:
Yes

SMT Lead Coplanarity:
(0.10 mm) .004" max (025-075)

Board Stacking:
For applications requiring more
than two connectors per board
contact ipg@samtec.com

RECOGNITIONS

For complete scope of
recognitions see
www.samtec.com/quality

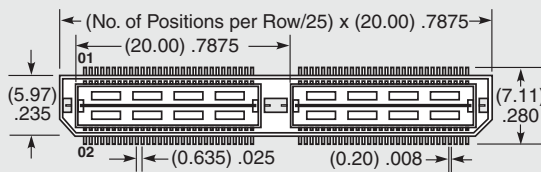


ALSO AVAILABLE (MOQ Required)

- 11 mm & 16 mm stack height
- 30 μ " (0.76 μ m) Gold
- Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 100 & 125 positions per row
- Edge Mount

Note:
Some lengths, styles and
options are non-standard,
non-returnable.

QTS	NO. OF POSITIONS PER ROW	LEAD STYLE	PLATING OPTION	D	A	OTHER OPTION
	-025, -050, -075 (50 total positions per bank)	Specify LEAD STYLE from chart.	-F = Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails -L = 10 μ " (0.25 μ m) Gold on Signal Pins and Ground Plane, Matte Tin on tails -C* = Electro-Polished Selective 50 μ " (1.27 μ m) min Au over 150 μ " (3.81 μ m) Ni on Signal Pins in contact area, 10 μ " (0.25 μ m) min Au over 50 μ " (1.27 μ m) Ni on Ground Plane in contact area, Matte Tin over 50 μ " (1.27 μ m) min Ni on all solder tails			-K = (7.00 mm) .275" DIA Polyimide film Pick & Place Pad -TR = Tape & Reel



*Note: -C Plating passes 10 year MFG testing

LEAD STYLE	A	MATED HEIGHT
-01	(4.27) .168	(5.00) .197
-02	(7.26) .286	(8.00) .315

Processing conditions will affect mated height. See SO Series for board space tolerances

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications.
Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.